APPLICA	BLE STAN	IDARD							
	OPERATING TEMPERATURE RANGE		-40°C TO + 85°C(NOTE 1)		STORAGE TEMPERATURE RANGE		-10°C TO + 60°C(NOTE 3)		
	OPERATING HUMIDITY RANGE		40% T0 + 80% (NOTE		RAGE 11DITY RAN	GE	40% TO + 70% (NO	)TE 3)	
	VOLTAGE		250V AC/DC	-		ONNECTOR	DF11-**DEP-	-	
<u> </u>	CURRENT		AWG24 : 2.5A	APP	LICABLE C	ABLE			
			AWG26 : 2.0A				AWG24 TO 28		
			AWG28 : 1.0A						
			SPEC	IFICATI	ONS	·			
	ТЕМ		TEST METHOD			REQ	JIREMENTS	QT	А
CONSTF GENERAL EX					10000		WINC		1.
MARKING	AMINATION		AND BY MEASURING INSTRU	JMENT.	ACCOR	NDING TO DRA	WING.	X	
-	IC CHARA							^	
CONTACT RE			C OR 1000 Hz).		30mΩ	MAX.		X	_
								~	
	VICAL CH				1		ANCE: 30mΩ MAX.		
IVIECHANICAL	LOPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.			0			V	
						RTS.		Х	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE					DISCONTINUITY OF 1µs.	Х	
		0.75 mm,	AT 2 h, FOR 3 DIRECTIONS.			DAMAGE, CRA RTS.	CK OR LOOSENESS OF	^	-
SHOCK		490 m/s <sup>2</sup> D	URATION OF PULSE 11 ms A	T 3 TIMES FOR			DISCONTINUITY OF 1µs.		
		DIRECTIONS.			-	DAMAGE, CRA RTS.	CK OR LOOSENESS OF	X	-
ENVIRO	NMENTAL	. CHARA	CTERISTICS		FAI	10.			
RAPID CHAN	GE OF	TEMPERA	TURE -55→ 5 TO 35→ 85→ 5	5 TO 35 °C	① COI	NTACT RESIST	ANCE: 30mΩ MAX.		
TEMPERATURE			TO 15 min	-	NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	-	
						<b>NIG</b> .			
		UNDER 5 0 EXPOSED	AT 40 ± 2 °C, 90 TO 95 %, 9	6 h.		NTACT RESIST	ANCE: 30mΩ MAX.		
DAMP HEAT (STEADY STA REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL AFTE	UDING THE TEI CONDENSING. LY TO THE CON ER MOUNTED C	EXPOSED MPERATURE IDITION OF L DN PCB, OPE	AT 40 $\pm$ 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR URATION TEMPERATURE ANI	JNUSED PROD	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI	CK OR LOOSENESS OF	X	-
DAMP HEAT (STEADY STA REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL AFTE	UDING THE TEL CONDENSING. LY TO THE CON	EXPOSED MPERATURE IDITION OF L DN PCB, OPE	AT 40 $\pm$ 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR URATION TEMPERATURE ANI	JNUSED PROD	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI	CK OR LOOSENESS OF	X	
COUN	UDING THE TEL CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT	AT 40 ± 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR U RATION TEMPERATURE AND TATION. ON OF REVISIONS H-00004374	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA	CHECKED	DA 2018	110
DAMP HEAT (STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOI	UDING THE TEL CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT	AT 40 ± 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR U RATION TEMPERATURE AND TATION.	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA	CHECKED SZ. ONO KJ. KATAYOSE	DA 2018 2005	110 010
COUN	UDING THE TEL CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT	AT 40 ± 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR U RATION TEMPERATURE AND TATION. ON OF REVISIONS H-00004374	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI PLIED FOR INT APPROVEE CHECKED	CHECKED SZ. 0N0 KJ. KATAYOSE TY. 0MA	DA 2018 2005/ 2005/	110 010 010
DAMP HEAT STEADY STA REMARKS NOTE 1:INCL NOTE 2:NO C NOTE 3:APPL AFTE STOI	UDING THE TEL CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT	AT 40 ± 2 °C, 90 TO 95 %, 9 RISE BY CURRENT ONG TERM STORAGE FOR U RATION TEMPERATURE AND TATION. ON OF REVISIONS H-00004374	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI PLIED FOR INT LIED FOR INT APPROVEE CHECKED DESIGNED	CHECKED SZ. ONO KJ. KATAYOSE TY. OMA I.O. DENPOUYA	DA 2018 2005 2005	110 010 010 010
COUN	UDING THE TEI CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT	AT 40 ± 2 °C, 90 TO 95 %, 9	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI PLIED FOR INT APPROVEE CHECKED DESIGNED DRAWN	CHECKED CHECKED SZ. 0N0 KJ. KATAYOSE TY. 0MA 10. DENPOUYA 10. DENPOUYA	DA 2018 20050 20050 20050 20050	110 010 010 010 010
DAMP HEAT STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOI	UDING THE TEL CONDENSING. Y TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT ESCRIPTIC DIS-H cifid , refe	AT 40 ± 2 °C, 90 TO 95 %, 9	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI PLIED FOR INT APPROVEE CHECKED DESIGNED DRAWN	CHECKED CHECKED SZ. 0N0 KJ. KATAYOSE TY. 0MA 10. DENPOUYA IO. DENPOUYA ELC-071511-	DA 2018 20050 20050 20050 20050	110 010 010 010 010
DAMP HEAT STEADY STA REMARKS NOTE 1:INCLI NOTE 2:NO C NOTE 3:APPL AFTE STOI	UDING THE TEI CONDENSING. LY TO THE CON ER MOUNTED C RAGE DURING	EXPOSED MPERATURE IDITION OF L DN PCB, OPE TRANSPORT TRANSPORT ESCRIPTIC DIS-H cifid , refe est AT:Ass PECIFIC	AT 40 ± 2 °C, 90 TO 95 %, 9	JNUSED PROD D HUMIDITY RA	1 COI 2 NO PAI	DAMAGE, CRA RTS. DRE MOUNTEI PLIED FOR INT APPROVEI CHECKED DESIGNED DRAWN NG NO.	CHECKED CHECKED SZ. 0N0 KJ. KATAYOSE TY. 0MA 10. DENPOUYA 10. DENPOUYA	DA 2018 2005/ 2005/ 2005/ 00-00	110 010 010 010 010